Final Product Change Notification

201309012F02

Issue Date: 28-Apr-2015
Effective Date: 10-Aug-2015

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Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[ ] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Details of this Change

Scheduled changes affect product types in SOT323 package only.
(1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)
Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 28-May-2015.

Production

Planned first shipment 01-Dec-2015

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201309012A	21-Dec-2013		Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 28-May-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC
BZB784-C3V9,115	934056301115
BZB784-C5V1,115	934056304115
BZB784-C5V6,115	934056305115
BZB784-C10,115	934056311115
BAS21SW,115	934063271115
BAS21AW,115	934063269115
BAS21SW,115	934063271115
BZB784-C5V1,115	934056304115
BAS21AW,115	934063269115
BZB784-C2V4,115	934057003115